

Description

DW03B has built-in high-precision voltage detection circuit and delay circuit, which can realize overcharge, overdischarge and overcurrent protection of the battery by detecting the voltage and current of the battery. The protection circuit is suitable for a single lithium ion/lithium polymer rechargeable battery.

Features

- High Precision Voltage Detection Function:

| | | |
|------------------------------------|--------|------------------------------|
| 1.Overcharge Protection Voltage | 4.300V | Accuracy: $\pm 50\text{mV}$ |
| 2.Overcharge Release Voltage | 4.100V | Accuracy: $\pm 50\text{mV}$ |
| 3.Overdischarge Protection Voltage | 2.800V | Accuracy: $\pm 100\text{mV}$ |
| 4.Overdischarge Release Voltage | 3.000V | Accuracy: $\pm 100\text{mV}$ |
| 5.Discharge OverCurrent Detection | 3.6A | |
| 6.Short Circuit Current Detection | 16.0A | |
| 7.Charging OverCurrent Detection | 3.4A | |

- Internal Detection Delay Time::

| | |
|----------------------------------|-------|
| 1.Overcharge Protection Delay | 1.0S |
| 2.Overdischarge Protection Delay | 128mS |
| 3.Delay of Discharge Overcurrent | 10mS |
| 4.Delay of Charge Overcurrent | 10mS |

- Charger Detection and Load Detection Function

| | |
|--|---------------------|
| ● Function of Charging 0V Battery | Allow |
| ● Dormancy Function | No |
| ● Conditions for Relieving Discharge Overcurrent | Disconnect The Load |
| ● The Release Voltage of Discharge Overcurrent State | V_{RIOV} |

- Low Current Consumption

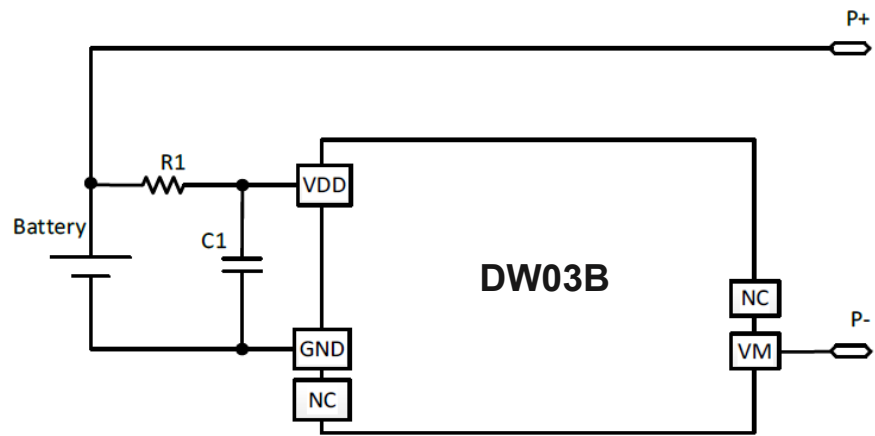
| | |
|-----------------|---|
| 1. At Work | 1.0 μA (Typ.) ($T_a=25^\circ\text{C}$) |
| 2.Overdischarge | 0.5 μA (Typ.) ($T_a=25^\circ\text{C}$) |

- On-Resistance Of internal Power N-MOSFET: 50m Ω
- Lead-Free and Halogen-Free
- Operating Temperature Range: $-40^\circ\text{C}\sim+85^\circ\text{C}$
- Available Package: SOT-23-5

Applications

- Protection IC for One-Cell Lithium-Ion /Lithium-Polymer Battery Pack

Typical Application Circuit

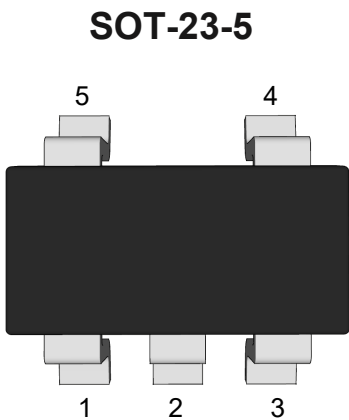


| Device Identification | Min. | Typ. | Max. | Unit |
|-----------------------|-------|------|------|------|
| R1 | 510 | 1000 | 1500 | Ω |
| C1 | 0.047 | 0.1 | 0.22 | μF |

Note :

1. The above parameters may be changed without notice.
2. The schematic diagram and parameters of IC are not used as the basis to ensure the circuit to work. Please make field measurement on the actual application circuit before setting the parameters.

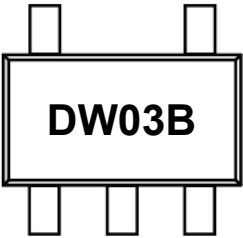
Pin Distribution



Functional Pin Description

| Pin NO. | Symbol | Pin Description |
|---------|--------|---|
| 1,5 | NC | Not Connected |
| 2 | GND | Ground Pin |
| 3 | VDD | Power Supply |
| 4 | VM | The charging and discharging current detection terminal is linked with the charger load or the load |

Ordering Information

| Orderable Device | Package | Reel (inch) | Package Qty (PCS) | Eco Plan ^{Note} | MSL Level | Marking Code |
|------------------|----------|-------------|-------------------|--------------------------|-----------|---|
| DW03B | SOT-23-5 | 7 | 3000 | RoHS & Green | MSL3 |  |

Note:

RoHS: TN defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials.

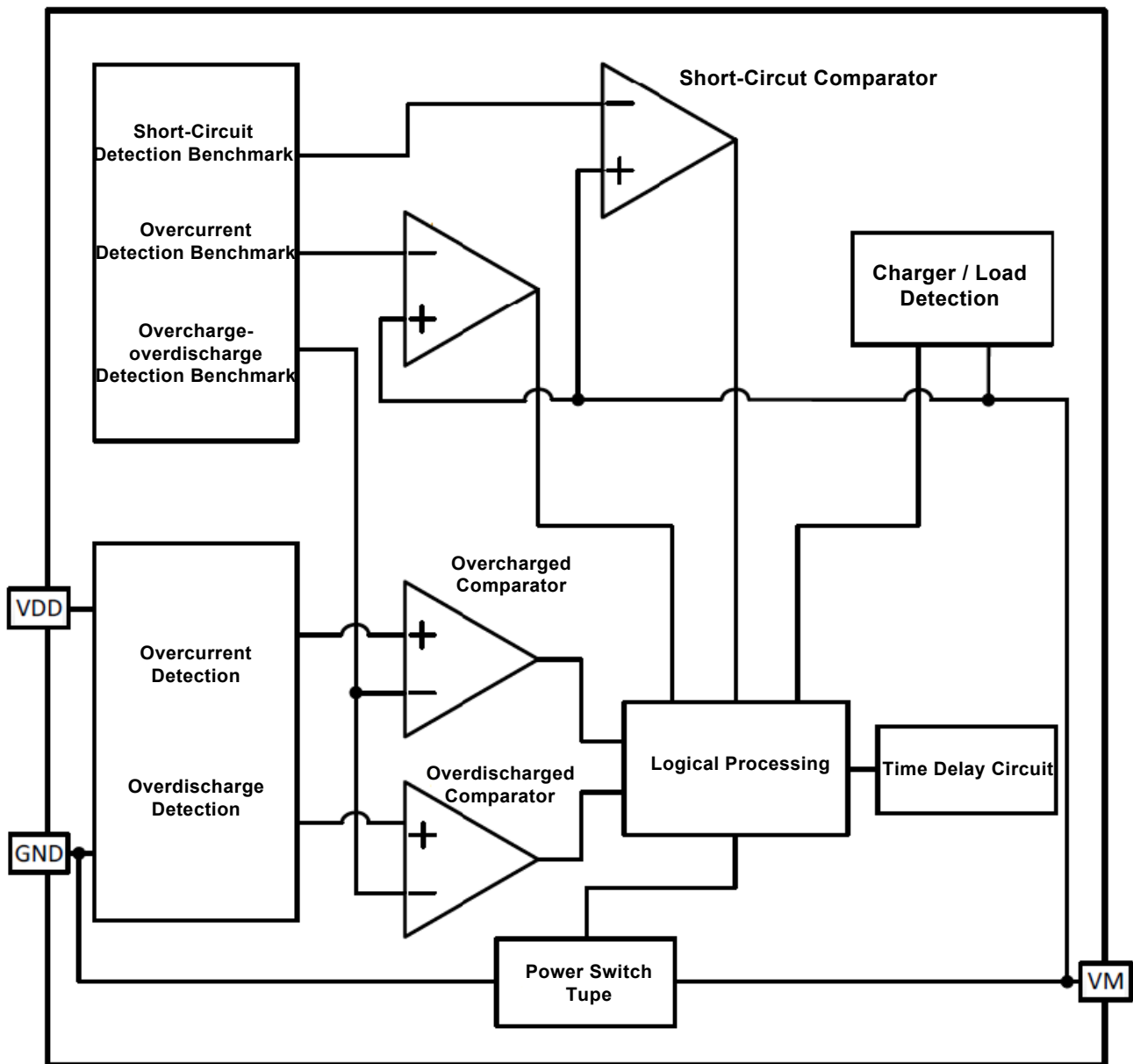
Green: TN defines "Green" to mean Halogen-Free and Antimony-Free.

Product List

1.Detection Voltage Sheet

| Device Name | $R_{DS(on)}$ | Overcharge Protection Voltage V_{OC} | Overcharge Release Voltage V_{OCR} | Overdischarge Protection Voltage V_{OD} | Overdischarge Release Voltage V_{ODR} | Discharge OverCurrent Detection I_{DI} | Short Circuit Current Detection I_{SHORT} | Charging OverCurrent Detection I_{CI} |
|-------------|--------------|--|--------------------------------------|---|---|--|---|---|
| DW03B | 50mΩ | 4.300V | 4.100V | 2.800V | 3.000V | 3.6A | 16A | 3.4A |

Block Diagram



Absolute Maximum Ratings ^{Note}

(T_A=25°C , unless otherwise noted.)

| Parameter | Symbol | Rating | Unit |
|-------------------------------------|-----------------------|-----------|------|
| Input Voltage Between VDD and GND | VDD | -0.3 ~6 | V |
| VM Pin Output Voltage | V _{VM} | -6 ~10 | V |
| Operating Ambient Temperature Range | T _{OPR} | -40 ~ 85 | °C |
| Storage Temperature Range | T _{STG} | -55 ~ 125 | °C |
| ESD(HBM State) | V _{ESD(HBM)} | 4000 | V |

Note :
The applied voltage exceeds the absolute maximum rating, which may cause irreversible damage to the chip.

Electrical Characteristics(T_A=25°C , unless otherwise noted.)

| Parameter | Symbol | Test Conditions | Min. | Typ. | Max. | Unit |
|---------------------------------------|--------------------|------------------------------|-------|-------|-------|------|
| Supply Voltage | VDD | | 1 | - | 5.5 | V |
| Normal working current | I _{VCC} | VDD=3.5V | 0.42 | 1.0 | 2.0 | μA |
| Consume current during overdischarge | I _{OPED} | VDD=1.5V | -- | 0.5 | 1.0 | μA |
| Overcharge Protection Voltage | V _{OC} | VDD=3.5→4.5V | 4.250 | 4.300 | 4.350 | V |
| Overcharge Release Voltage | V _{OCR} | VDD=4.5→3.5V | 4.050 | 4.100 | 4.150 | V |
| Overdischarge Protection Voltage | V _{OD} | VDD=3.5→2.0V | 2.700 | 2.800 | 2.900 | V |
| Overdischarge Release Voltage | V _{ODR} | VDD=2.0→3.5V | 2.900 | 3.000 | 3.100 | V |
| Discharge OverCurrent Detection | I _{DI} | VM-GND=0→0.2V | 2.7 | 3.6 | 4.5 | A |
| Charging OverCurrent Detection | I _{CI} | GND-VM=0→0.3V | 2.5 | 3.4 | 4.3 | A |
| Overcharge Protection Delay | T _{OC} | VDD=3.5→4.5V | 500 | 1000 | 1500 | ms |
| Overdischarge Protection Delay | T _{OD} | VDD=3.5→2.0V | 64 | 128 | 192 | ms |
| Delay of Discharge Overcurrent | T _{DI} | VM-GND=0→0.2V | 5 | 10 | 20 | ms |
| Delay of Charge Overcurrent | T _{CI} | GND-VM=0→0.3V | 5 | 10 | 20 | ms |
| Short Circuit Current Detection | I _{SHORT} | VM-GND=0→1.5V | 8 | 16 | 24 | A |
| Short Circuit Delay | T _{SHORT} | VM-GND=0→1.5V | 100 | 250 | 400 | μs |
| 0V Charging, Charger Starting Voltage | V _{0CH} | Allow charging to 0V battery | 0.0 | 1.5 | 2.0 | V |

Function Description

1. Normal Operating State

This IC continuously detects the battery voltage connected between the VDD and GND terminals, as well as the current flowing between the VM and GND terminals, to control charge and discharge. When the battery voltage is above the overdischarge protection voltage (V_{OD}) and below the overcharge protection voltage (V_{OC}), and the current flowing through the VM terminal to GND is between the charge overcurrent protection threshold (I_{CI}) and discharge overcurrent protection threshold (I_{DI}), the internal MOSFET of the IC is switched on. This state is called "normal working state". In this state, the MOSFET can be charged and discharged normally.

2. Overcharge State

When during the charging process under normal conditions, when the battery voltage is higher than the overcharge detection voltage (V_{OC}), and the duration reaches the overcharge voltage detection delay time (T_{OC}) or longer, the internal MOSFET of IC will turn off and stop charging, this situation is called overcharge voltage protection. The overcharge state can be lifted under the following two conditions:

(1). $VM < V_{LD}$, when the battery voltage is lowered below the overcharge release voltage (V_{OCR}), the overcharge state will be released.

(2). $VM > V_{LD}$, when the battery voltage is reduced to the overcharge protection voltage (V_{OC}) below, the overcharge state is lifted and returned to the normal working state, this function is called the load detection function.

Here (V_{LD}) = $I_{DI} \cdot R_{SS(ON)}$, is the load detection voltage set inside the IC.

3. Overdischarge State

After the battery voltage drops below V_{OD} and the well continues T_{OD} for a period of time, the internal MOSFET of IC will turn off and stop discharging, which is called the overdischarge state. When the MOSFET inside the IC is turned off, the VM will be pulled up to VDD by the internal pull-up resistor R_{VMD} , and the IC power consumption will be reduced to I_{OPED} .

After entering the overdischarge state, to remove the overdischarge state and return to the normal state, there are several situations:

(1) Connect the charger, if $VM < 0V$ (typical value), when the battery voltage is higher than the overdischarge protection voltage (V_{OD}), the overdischarge state is lifted and restored to the normal working state, this function is called the charger detection function.

(2) Connect the charger, if $VM > 0V$ (typical value), when the battery voltage is higher than the overdischarge release voltage (V_{ODR}), the overdischarge state is lifted and restored to the normal working state.

(3) When the charger is not connected, when the battery voltage is higher than the overdischarge release voltage (V_{ODR}), the overdischarge state is released and returned to the normal working state, that is, "no sleep function".

4. Discharge Overcurrent State

In the normal working state of the battery, the IC continuously detects the discharge current through the VM terminal voltage. If the discharge current exceeds the discharge current Limiting value (I_{DI}), and this state lasts longer than the discharge overcurrent Protection Delay time (T_{DI}), the internal MOSFET of IC will turn off and stop discharging. This state is called the discharge overcurrent state. If the discharge current exceeds the short-circuit protection current value, and this state lasts longer than the load short-circuit protection delay time (T_{SHORT}), the MOSFET inside the IC will turn off and stop discharging. This state is called the "load short-circuit state".

Discharge overcurrent state release condition "disconnect load" and discharge overcurrent state release voltage " V_{RIOV} "

In the discharge overcurrent state, the VM terminal inside the chip and the GND terminal can be connected through the R_{VMS} resistor. However, during the connection to the load, the VM terminal voltage changes to the VDD terminal voltage due to the connection to the load. If the connection to the load is disconnected, the VM terminal reverts to the GND terminal voltage. When the VM terminal voltage drops below V_{RIOV} , the discharge overcurrent state can be lifted.

5. Charge Overcurrent Protection

For a battery in normal working condition, if the current value flowing through GND to VM exceeds the charge overcurrent protection value (I_{CI}) during charging, and the state lasts longer than the charge overcurrent protection Delay time (T_{CI}), the internal MOSFET of IC will turn off and stop charging. This state is called charging overcurrent state. After entering the state of charge overcurrent detection, if disconnect the charger to make the flow through GND to VM, When the current of the VM terminal is lower than the overcurrent protection value (I_{CI}), the charging overcurrent state is removed and returned to the normal working state.

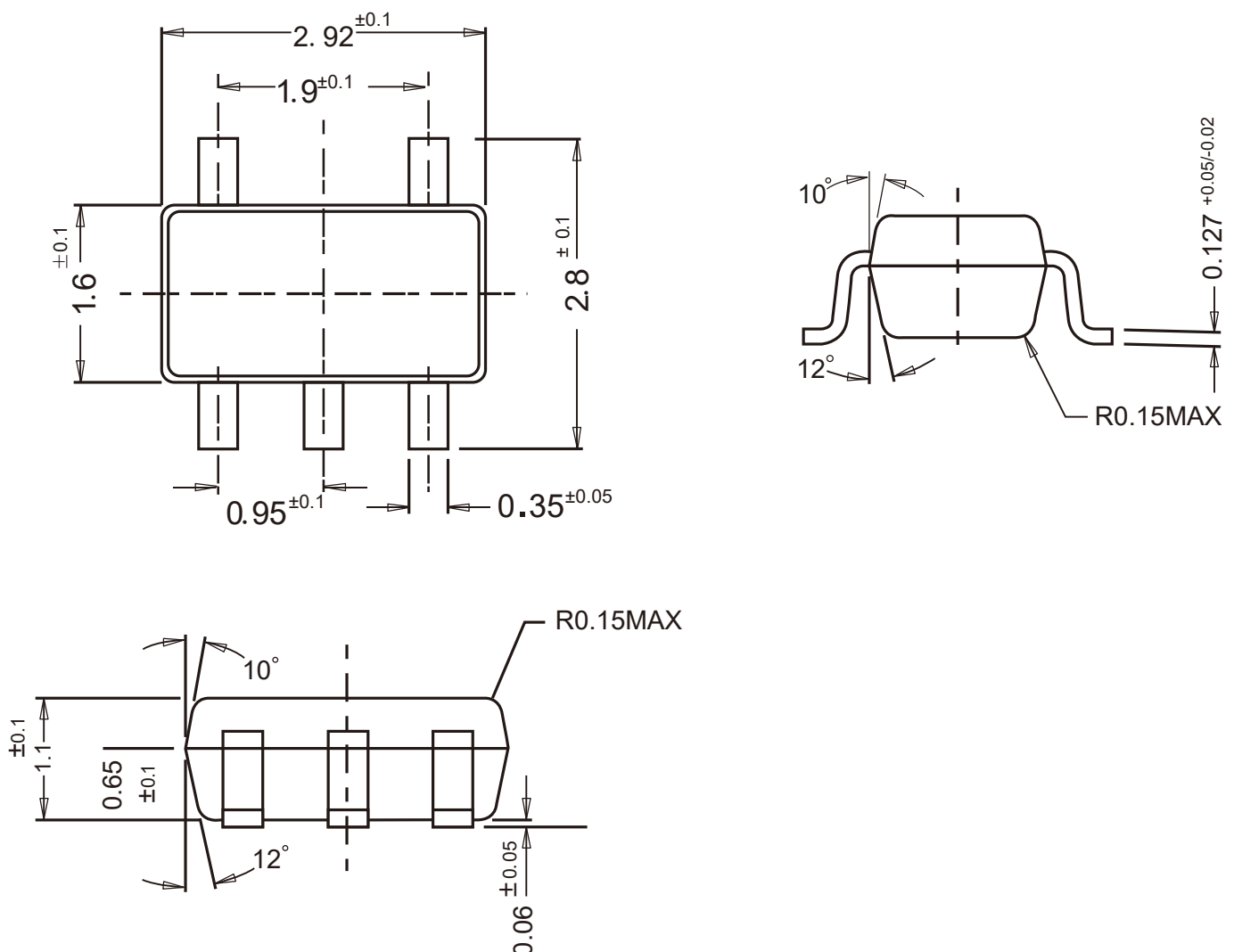
6. Charging Function to 0V Battery(Allowed)

This function is used to recharge the battery that has self-discharged to 0V. When the charger voltage connected between the positive battery (P+) and the negative battery (P-) is higher than the charger starting voltage (V_{0CH}) to charge the 0V battery, the IC internal charge control MOSFET will switch on and start charging. When the battery voltage is higher than the overdischarge protection voltage (V_{OD}), the IC enters the normal working state.

Note: Please ask the battery supplier to confirm whether the purchased battery has the "allow charging to the 0V battery" function or the "do not charge to the 0V battery" function".

Package Outline SOT-23-5


Dimensions in mm



Contact Information

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For additional information, please contact your local Sales Representative.

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